RoHS



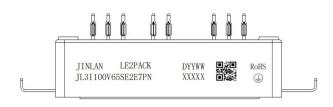
# JL3I100V65SE2E7PN

### 3-Level NPC Inverter Module with 650V Trench Stop IGBTs

#### **Features**

- Electrical features
  - 650V Trench Stop IGBTs
  - Low Inductive Design
  - Low Switching Losses
  - Low Inductive Layout
  - Thermistor
- · Mechanical features
  - Compact Design
  - Pressfit contact technology
  - Al<sub>2</sub>O<sub>3</sub> Substrate with Low Thermal Resistance

#### LE2 Pack



### **Typical Applications**

- 3-Level-Applications
- Solar Applications
- UPS Systems

**JINLAN** 

JL3I100V65SE2E7PN

YYWW

**XXXXX** 

QR code

= Company Name

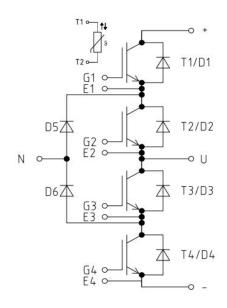
= Specific Device Code

= Year and Work Week Code

= Serial Number

= Custom Assembly Information

### **Description**





## Package Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	Visol	RMS,f=50Hz,t=60s	2.5	kV
Internal isolation		basic insulation(class 1,IEC 61140)	Al <sub>2</sub> O <sub>3</sub>	
Creepage distance	d <sub>creep</sub>	terminal to heatsink	11.5	mm
Clearance	d <sub>clear</sub>	terminal to heatsink	10	mm
Comparative tracking index (electrical)	СТІ		>200	
RTI Elec.	RTI	housing	140	$^{\circ}$

# Package Characteristic values

					Values		
Parameter	Symbol	Note or test condit	Note or test condition		Тур.	Max.	Unit
Stray Inductance	LCE				15		nH
Module Lead Resistance, Terminal to Chip	Rcc'+EE'				2.00		mΩ
Storage Temperature Range	T <sub>STG</sub>			-40		125	C
Mounting torque for module mounting	M	-Mounting according to valid application note		40		80	N
Weight	G				39	1	g



## **IGBT** (T1, T2, T3, T4)

### Absolute Maximum Ratings (Tc = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage	650	V
$V_{GES}$	Gate-Emitter Voltage	±30	V
I <sub>CDC</sub>	Continuous Collector Current @ Tc = 80°C (TJMAX = 175°C)	100	А
Ісм	Pulsed Collector Current, t <sub>p</sub> limited by T <sub>vj max</sub>	200	А
Tjmax	Maximum Junction Temperature	175	°C
D	Power Dissipation @ T <sub>C</sub> = 25°C	318	W
P <sub>D</sub>	Power Dissipation @T <sub>C</sub> = 100 °C	127	W

**Characteristics** (Tc=25<sup>o</sup>C unless otherwise noted)

Symbol	Parameter	Test Co	ndition	Min	Тур	Max	Unit
		I <sub>C</sub> =100A,	T <sub>vj</sub> = 25 °C	-	1.25	1.70	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	V <sub>GE</sub> = 15V	T <sub>vj</sub> = 175 °C		1.45		V
$V_{\text{GE(TH)}}$	Gate-Emitter Threshold Voltage	I <sub>C</sub> =1mA,	V <sub>CE</sub> =VGE	4.0		5.5	٧
I <sub>CES</sub>	Collector-Emitter Cutoff Current	V <sub>GE</sub> = 0 V,	V <sub>CE</sub> = 650 V			100	μΑ
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE} = \pm 30 \text{ V}, V_{CI}$	<sub>E</sub> = 0 V, T <sub>vj</sub> = 25°C			±100	nA
RGint	Internal Gate Resistance	T <sub>vj</sub> =	25°C		0.8	-	Ω
Cies	Input Capacitance	V <sub>CE</sub> =25V	′,V <sub>GE</sub> =0V,		7250	-	рF
Coes	Output capacitance		MHz		320	ı	рF
Cres	Reverse Transfer			-	48	ı	рF
$Q_G$	Gate Charge	V <sub>CE</sub> = 480 V, I <sub>C</sub> = 100 A V <sub>GE</sub> = -5 V to +15 V			0.121	ı	μC
td(on)	Turn-On Delay Time				65		
tr	Rise Time	$V_{CE}$ =400V, $I_{C}$ =100A, $V_{GE}$ == -5 V to +15 V, $R_{g}$ =5 $\Omega$ Inductive Load Tvj=25°C			42	-	
td(off)	Turn-off Delay Time				178	1	ns
tf	Fall Time				32		
Eon	Turn-On Switching Loss per Pulse				5.2	-	
Eoff	Turn Off Switching Loss per Pulse				2.8		mJ
td(on)	Turn-On Delay Time				72		
tr	Rise Time				50		
td(off)	Turn-off Delay Time	V <sub>CE</sub> =400V	′ I <sub>C</sub> =100A		194	-	ns
tf	Fall Time	V <sub>GE</sub> == −5 V to	$V_{GE}=400V, C=100A,$ $V_{GE}=-5 V \text{ to } +15 V, R_g=5\Omega$		38	-	
Eon	Turn-on Switching Loss per Pulse	T <sub>j</sub> =175°C			6.6		
Eoff	Turn Off Switching Loss per Pulse				4.0		mJ
RthJC	Thermal resistance	Junction-to-Ca	ase (per IGBT)		0.35		K/W
T <sub>vj op</sub>		Temperature under	switching conditions	-40		150 <sup>1)</sup>	$^{\circ}$

<sup>&</sup>lt;sup>1)</sup>T<sub>vjop</sub> > 150°C is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.



### Diode (D1, D2, D3, D4)

### Absolute Maximum Ratings (Tc = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage	650	V
I <sub>F</sub>	Diode Continuous Forward Current	100	Α
I <sub>FM</sub>	Diode Maximum Forward Current t <sub>p</sub> =1ms	200	Α

#### Characteristics (Tc=25℃ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
.,	Diada Farmand Valta na	I <sub>F</sub> = 100 A, T <sub>J</sub> = 25°C		1.45	2.00	.,
VF	V <sub>F</sub> Diode Forward Voltage	I <sub>F</sub> = 100 A, T <sub>J</sub> = 175°C		1.35	-	V
Trr	Reverse Recovery Time	Vc=400V		176	1	ns
IRM	Peak Reverse Recovery Current	$V_{GE} = -5 \text{ V to } +15 \text{ V}$		20.7	ŀ	Α
Qrr	Recovered Charge	$I_F=100A,R_g=5\Omega$ $Tvj=25^{\circ}C$		2.9	I	μC
Erec	Reverse Recovery Energy	17]-23 0		0.4	I	mJ
Trr	Reverse Recovery Time	V <sub>CE</sub> =400V		237	-	ns
lгм	Peak Reverse Recovery Current	$V_{GE} = -5 \text{ V to } +15 \text{ V}$		39.3	-	Α
Qrr	Recovered Charge	$I_F$ =100A, $R_g$ =5Ω, $T_V$ i=175°C		7.0	1	μC
Erec	Reverse Recovery Energy	- 1VJ-173 C		0.6	1	mJ
RthJC	Thermal resistance	Junction-to-Case (per diode)		0.4	1	K/W
T <sub>vj op</sub>		Temperature under switching conditions	-40		150 <sup>2)</sup>	$^{\circ}$

<sup>&</sup>lt;sup>2)</sup>T<sub>vjop</sub> > 150 ℃ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

### Diode (D5, D6)

### **Absolute Maximum Ratings** (Tc = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	650	V
I <sub>F</sub>	Diode Continuous Forward Current	100	Α
I <sub>FM</sub>	Diode Maximum Forward Current t <sub>p</sub> =1ms	200	Α

#### Characteristics (Tc=25℃ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
.,	Diada Farmand Valtana	I <sub>F</sub> = 100 A, T <sub>J</sub> = 25°C		1.35	1.90	.,
VF	V <sub>F</sub> Diode Forward Voltage	I <sub>F</sub> = 100 A, T <sub>J</sub> = 175°C		1.25	1	V
Trr	Reverse Recovery Time	V =400V		135	ŀ	ns
IRM	Peak Reverse Recovery Current	$V_{CE}=400V$ $V_{GE}==-5 V \text{ to } +15 V$		15.9	ŀ	Α
Qrr	Recovered Charge	$I_F$ =100A, $R_g$ =5Ω $Tv_j$ =25°C		2.2	ŀ	μC
Erec	Reverse Recovery Energy	1 4 j = 2 5 0		0.3	ŀ	mJ
Trr	Reverse Recovery Time	V <sub>CE</sub> =400V		182	1	ns
IRM	Peak Reverse Recovery Current	$V_{GE} = -5 \text{ V to } +15 \text{ V}$		30.2		Α
Qrr	Recovered Charge	$I_F$ =100A, $R_g$ =5 $\Omega$ , Tvj=175°C		5.4	1	μC
Erec	Reverse Recovery Energy	TVJ=173 C		0.5	1	mJ
RthJC	Thermal resistance	Junction-to-Case (per diode)		0.31		K/W
T <sub>vj op</sub>		Temperature under switching conditions	-40		150 <sup>3)</sup>	$^{\circ}$

 $<sup>^{3)}</sup>T_{v_{j}\,op}$  > 150  $^{\circ}$ C is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.



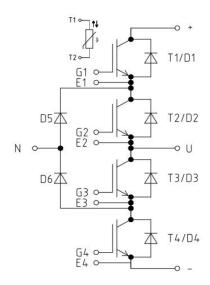
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# NTC Characteristics (Tc = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
R <sub>25</sub>	Rated Resistance			5.0		kΩ
ΔR/R	Deviation of R100	Tc=100 °C,R100=493.3Ω	-5		5	%
P <sub>25</sub>	Power Dissipation				20.0	mW
B <sub>25/50</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/50</sub> (1/T <sub>2</sub> - 1/(298.15K))]		3375		K
B <sub>25/80</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/80</sub> (1/T <sub>2</sub> - 1/(298.15K))]		3411		K
B <sub>25/100</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/100</sub> (1/T <sub>2</sub> - 1/(298.15K))]		3433		K

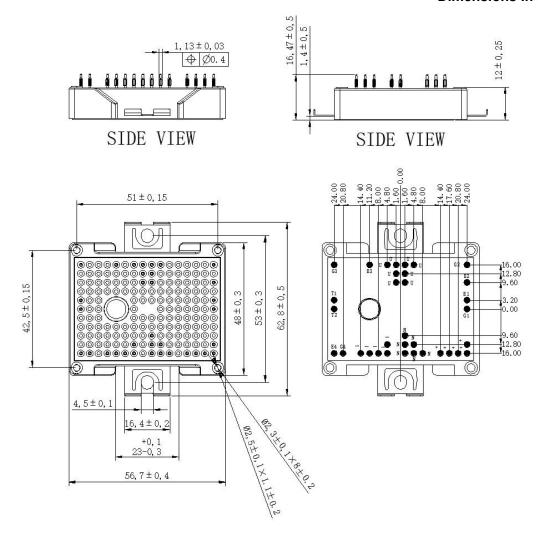


### **CIRCUIT DIAGRAM**



#### **PACKAGE DIMENSION**

#### **Dimensions in Millimeters**





### **REVISION HISTORY**

Document version	Date of release	Description of changes
Rev.00	2024-10-30	Preview
Rev.01	2025-1-14	PIN location degree modification



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